

**Amendments to the Claims**

This listing of claims will replace all prior listings of claims in the application.

**Listing of Claims**

1. (Currently Amended) An electroless copper plating solution, containing a water-soluble nitrogen-containing polymer, ~~and, glyoxylic acid and phosphinic acid as reducing agents~~ in the electroless copper plating solution.

2. (Original) An electroless copper plating solution according to Claim 1, wherein the water-soluble nitrogen-containing polymer is a polyacrylamide or a polyethyleneimine.

3. (Previously Presented) An electroless copper plating solution according to Claim 1, wherein a weight average molecular weight (Mw) of the water-soluble nitrogen-containing polymer is at least 100,000, and Mw/Mn (Mn is a number average molecular weight thereof) is 10.0 or less.

4. (Canceled)

5. (Previously Presented) An electroless copper plating method, performed using the electroless copper plating solution according to Claim 1.